TITLE OF THE INVENTION

PROCESS OF PACKAGING SEMICONDUCTOR CHIP IN SYNTHETIC RESIN PRODUCED FROM PRESSURIZED GRANULAR SYNTHETIC RESIN AND MOLDING DIE USED THEREIN

ABSTRACT

A semiconductor chip (44) mounted on a lead frame (45) is sealed in a synthetic resin package through a molding process, and pressure is applied to synthetic resin (46) softened from granular synthetic resin (43) so as to evacuate the air from the synthetic resin before injecting the synthetic resin into cavities (25/26) formed in a molding die (21), thereby preventing the synthetic resin package from void.

figure 4C